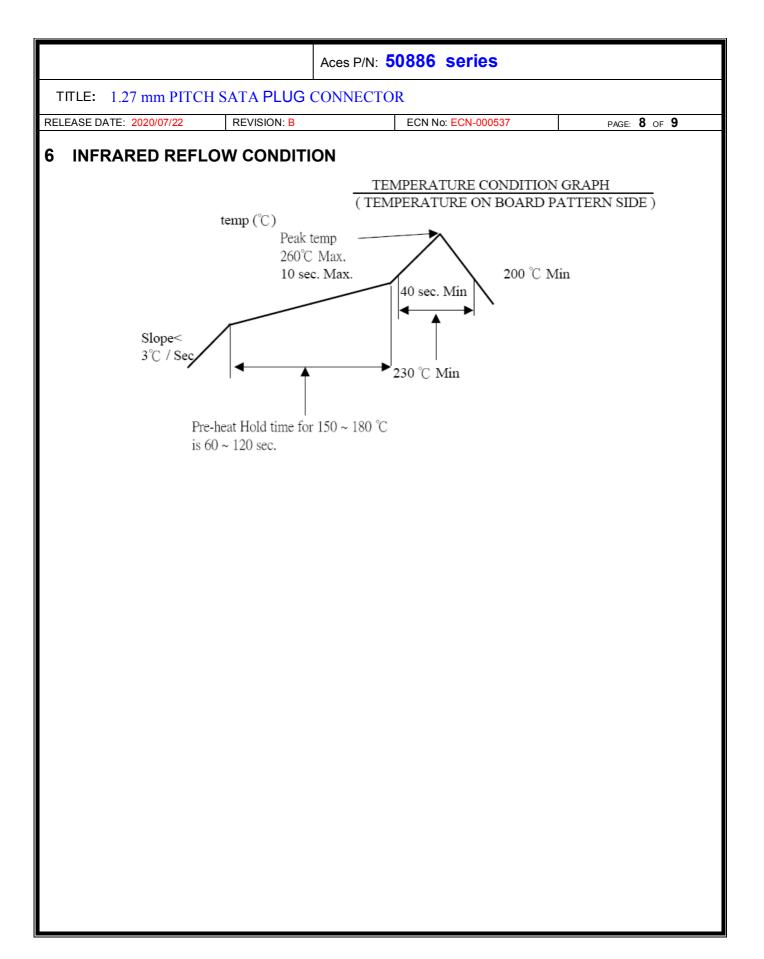
			Ace	es P/N: 50886 series							
TITLE: 1.27 mm PITCH SATA PLUG CONNECTOR											
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2	SCOPE										
	- 1 ·										
	This specification covers performance, tests and quality requirements for the 1.27 mm pith SATA connector series products.										
3											
3	APPLICABLE DOCUMENTS										
	EIA-364: ELECTRONICS INDUSTRIES ASSOCIATION										
	DEQUIDE										
4	REQUIRE	MENIS									
	4.1 Design and Construction										
	4.1.1 Product shall be of design, construction and physical dimensions specified on applicable product drawing.										
	4.1.2	All materials	conform to R.o.H.S. a	and the standard depends on TQ-WI-1	40101.						
	4.2 Material	s and Finisl	h								
	4.2.1		gh performance cop fer to the drawing.	oper alloy							
			hermoplastic, High								
	4.2.3		h performance copp fer to the drawing.	per alloy							
	4.2.4		k: High performance fer to the drawing.	e copper alloy							
	4.3 Ratings		0								
			Itage less than 36 v	olts AC (per pin)							
		Voltage: 1 Current: D	5 Volts AC C 1.5 Amperes								
	4.3.4	Operating 1	remperature : -55℃	to +85 ℃							

	Aces P/N: 5088	6 sei	ries				
-E: 1.27 mm PITCH S	ATA PLUG CONNECTOR						
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Performance	s and Procedures Summary						
Item	Requirement		Sta	ndard			
Examination of Product	Product shall meet requirement applicable product drawing and specification.		/isual, dimension	and and functional per y inspection plan. ndard easure by dry circuit, Max. s, apply adjacent terminals. a level for 1 minute. ent contacts of d connector omain Reflectometer differential mode with a V+) and a negative b. Define a reflected e: Vdiff=V+ - V- onnected to the risetime ured 20% - 80% Vp). e used to slow the see NOTE 2) VR to the sample races. Calibrate the system (see NOTE 3) ecord the maximum and s of the near end dance. or to a test PCB cent pins in parallel for ninimum number connector type) cent pins in parallel for inimum number connector type) rent of three times the er contact to the supply hrough the return pins ature rise when thermal			
	ELECTRIC	AL		I and functional pernspection plan. lard sure by dry circuit, ax. apply jacent terminals. evel for 1 minute. t contacts of onnector ain Reflectometer remential mode with a) and a negative Define a reflected /diff=V+ - V-nected to the risetime d 20% - 80% Vp). sed to slow the NOTE 2) to the sample es. Calibrate the stem (see NOTE 3) rd the maximum and f the near end nce. o a test PCB nt pins in parallel for imum number nnector type) nt pins in parallel for			
ltem	Requirement		Stan	dard			
Low Level Contact Resistance	$\frac{30 \text{ m } \Omega}{15 \text{ m } \Omega}$ Max.(initial)per contact	<mark>20m</mark> (EIA	V Max., <mark>100mA</mark> I \-364-23)	asure by dry circuit, Max. , apply djacent terminals. level for 1 minute.			
Insulation Resistance	1000 M Ω Min.	<mark>500</mark> (EIA	Unmated connectors, apply 500 V DC between adjacent terminals. (EIA-364-21)				
Dielectric Withstanding Voltage	No discharge, flashover or breakdown. Current leakage: 0.5 mA max.	Test mate asse	 500 VAC Min. at sea level for 1 minute. Test between adjacent contacts of mated and unmated connector assemblies (EIA-364-20) 1. Set the Time Domain Reflectometer (TDR) pulse in differential mode with a positive going (V+) and a negative going pulse (V-). Define a reflected differential trace: Vdiff=V+ - V- 2. With the TDR connected to the risetime reference trace, verify an input risetime of 70 ps (measured 20% - 80% Vp). Filtering may be used to slow the system down (see NOTE 2) 3. Connect the TDR to the sample measurement traces. Calibrate the instrument and system (see NOTE 3) 4. Measure and record the maximum and minimum values of the near end connector impedance. 1. Mount connector to a test PCB 2. Wire three adjacent pins in parallel for supply (or the minimum number required by the connector type) 3. Wire three adjacent pins in parallel for return (or the minimum number required by the connector type) 4. Apply a DC current of three times the current rating per contact to the supply pins ,returning through the return pins 5. Record temperature rise when thermal equilibrium is reached. 				
Mated Connector Impedance (Signal Port)	100 Ω ±15%	1. 3 (2. 1 3. (4. 1					
Temperature Rise	30℃ Max. Change allowed	2. 3. 4. 5.					

	Aces P/N	: 50886 se	ries				
: 1.27 mm PITCH SA	TA PLUG CONNEC	TOR					
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	MECH	ANICAL					
ltem	Requirer		Sta	ndard			
Durability	50cycles. (For Reference)	ך t 1 (The sample should be mounted in the tester and fully mated and unmated the number of cycles specified at the rate of 10 ± 3 mm/min. (200 cycles per hour max.) (EIA-364-09)				
Screw Torque	2.5Kgf-cm Max.	s	screw on conne	que driver to fix the nnector without housing oken and screw thread			
Contact Retention Force	0.30Kgf Min.	2	Operation Speed : 25.4 ± 3 mm/minute. Measure the contact retention force with Tensile strength tester.				
Lock / Housing Retention Force	0.25kgf MIN.	kgf MIN.		Apply axial pull out force at the speed rate of 25.4 ± 3 mm/minute. On the Loc assembled in the housing.			
Vibration (Random)	1 µs Max.	F r s r a (perpendicular di mating halves s so as not to con motion of one co another	hould be rigidly fixed tribute to the relative ontact against st conditions VII, test			
Shock (Mechanical)	1 µs Max.	: r i t c e 1	Subject mated connectors to 30 G's half-sine shock pulses of 11 milliseconds duration. Three shock in each direction shall be applied alo the three mutually perpendicular ax of the test specimen (18 shocks). T electrical load condition shall be DO 100mA maximum for all contacts. (EIA-364-27, test condition H)				
		NMENTAL		d be mounted in the ted and unmated the specified at the rate of ur max.) river to fix the ctor without housing and screw thread d : ute. tact retention force ngth tester. t force at the speed n/minute. On the Lock nousing. ch of 3 mutually rections, Both nould be rigidly fixed ribute to the relative ntact against t conditions VII, test) nectors to nock pulses of 11 ion. Three shocks hall be applied along perpendicular axes en (18 shocks). The dition shall be DC for all contacts. t condition H) ndard C~180°C, 60~90sec. n., 40sec Min. 50°C Max, ax.			
ltem	Requirer	ment	Sta				
Resistance to Reflow Soldering Heat	Second Reflow proc taken after the productemperature has down condition. See Product Qualific Sequence Group 8	uct H wn to room F cation and Test	Pre Heat ∶ 150℃ Heat ∶ 230℃ Mi Peak Temp. ∶ 2 10sec M Reflow number	60°C Max, lax.			

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Thermal Shock	See Product Qualification and Sequence Group 4	Condition for 10 0 Test 1 cycles: -55 +0/-3 ℃, 30 +85 +3/-0 ℃, 30	Mate module and subject to follow condition for 10 cycles. 1 cycles: -55 +0/-3 °C, 30 minutes +85 +3/-0 °C, 30 minutes (EIA 364-32 Test Condition I)			
Humidity	See Product Qualification and Sequence Group 4	Test 40℃, 90~95% 96 hours.				
Temperature Life	See Product Qualification and Sequence Group 1	Test temperature life hours.	(EIA-364-17, Test condition III Method A)			
Salt Spray (Only For Gold Plating)	See Product Qualification and Sequence Group11	(I) Gold flash for	% salt-solution 5℃			
Solder ability	Solder able area shall have minimum of 95% solder covera	into solder bath	5-10 sec. And then Temperature at			
Hand Soldering Temperature Resistance	Appearance: No damage	T≧350°C, 3sec	at least.			

Note 1. Flowing Mixed Gas shell be conduct by customer request. **Note 2.** Test Plug: Molex SATA P/N: 87703-0001



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7 PRODUCT QUALIFICATION AND TEST SEQUENCE											
	Test Group										
Test or Examination	1	2	3	4	5	6	7	8	9	10	11
		 			Test S	Sequenc	;e	<u>. </u>			
Examination of Product	1、8	1、6	1、5	1 • 8				2			1、4
Low Level Contact Resistance	2、4、 6	2、5	2、4				[T			2、5
Insulation Resistance	Ē			2、6				Τ	「		
Dielectric Withstanding Voltage				3 \ 7				Γ			
Temperature Rise	7										
Durability			3					<u> </u>			
Vibration (Random)		3									
Shock (Mechanical)		4									
Thermal Shock				4				<u> </u>			
Humidity				5							
Temperature Life	3										
Reseating (Manually Unplug/Plug Three Times)	5										
Salt Spray(Only For Gold Plating)											3
Solder ability	<u> </u>						1	Τ	「 <u> </u>		
Resistance to Soldering Heat			 					1			
Mated Connector Impedance (Signal Port)						1					
Screw Torque	<u> </u>							Γ	1		
Contact Retention Force	<u> </u>							<u> </u>		1	
Lock /Housing Retention Force					1						
Sample Size	2	4	4	4	4	4	4	2	4	4	4
											<u> </u>